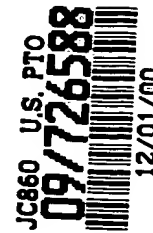




PATENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

Sir:



The patent application of

Inventor(s): ABE ET AL

For: THERMOSETTING SOLDERING FLUX AND SOLDERING  
PROCESS

is attached for filing.

- [X] This application claims the priority of Japanese Patent Application  
No. 344979/1999 filed on December 3, 1999.
- [X] This application is being filed in Japanese.
- [X] This application is being filed without a declaration or fee.

Respectfully submitted,

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Date: December 1, 2000

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## VERIFICATION OF A TRANSLATION

I, the below named translator, hereby declare that:

My name and post office address are as stated below;

That I am knowledgeable in the English language and in the language in which the below identified application was filed, and that I believe the English translation of the United States Patent Application No. 09/726,588 is an accurate and complete translation of the above identified application as filed.

Dated April 10, 2001

Full name of the translator

CHIEKO HIROSE

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